**Regarding claim 1**. A downhole tool, comprising:  
a plug section located within an outer surface of the downhole tool;  
a bonded diamond compact (BDC) construct including:  
a BDC element; and  
an encapsulation layer at least partially encapsulating the BDC element, wherein the BDC construct is disposed within the plug section of the downhole tool;  
  
a tungsten carbide binder cloth chemically coupled to a surface of the plug section and forming a first layer thereon; and  
a metal matrix cloth chemically coupled to the first layer and forming a second layer on the surface of the plug section.   
   
**Regarding claim 2**. The downhole tool of claim 1, wherein the encapsulation layer fully encapsulates the BDC element.   
   
**Regarding claim 3**. The downhole tool of claim 1, comprising at least one of the soup consisting of a drill bit, a push-the-bit pad and a mud motor bearing assembly.   
   
**Regarding claim 4**. The downhole tool of claim 1, wherein the BDC element and the encapsulation layer form an interface there between to secure the encapsulation layer to the BDC element.   
   
**Regarding claim 5**. The downhole tool of claim 4, wherein the interface between the BDC element and the encapsulation layer includes a chemical bond.   
   
**Regarding claim 6**. The downhole tool of claim 1, wherein the encapsulation layer includes at least one of a mixture of boron nitride and diamond, a mixture of tungsten and carbon and combinations thereof.   
   
**Regarding claim 7**. The downhole tool of claim 1, wherein the first and second layers are chemically coupled to the BDC construct.   
   
**Regarding claim 8**. A wear resistant downhole tool component assembly, comprising:  
a wear surface defined on one of the group consisting of a drill bit, a push the bit pad, and a mud motor hearing assembly, wherein the wear surface includes a plug section having a plurality of plugs; and  
a BDC construct attached to the wear surface, wherein the BDC construct is attached to bottom and side surfaces of a plug of the plurality of plugs, the BDC construct including a BDC element and an encapsulation layer fully encapsulating the BDC element, wherein the encapsulation layer forms an insulating layer over the BDC element.   
   
**Regarding claim 9**. The assembly of claim 8, wherein the encapsulation layer has a lower thermal conductivity than the BDC element.   
   
**Regarding claim 10**. The assembly of claim 8, wherein the encapsulation layer has a higher specific heat than the BDC element.   
   
**Regarding claim 11**. The assembly of claim 8, wherein the BDC construct has a cylindrical shape.   
   
**Regarding claim 12**. The assembly of claim 8, wherein the encapsulation layer has a uniform thickness.   
   
**Regarding claim 13**. The assembly of claim 8, wherein the encapsulation layer includes a mixture of a polymer and a metal.   
   
**Regarding claim 14**. A downhole tool, comprising:  
a plug section defined on an outer surface of the downhole tool, the plug section including a plurality of cavities therein;  
a plurality of BDC constructs, each BDC construct received in a cavity of the plurality of cavities, and each BDC construct formed of a bonded diamond compact (BDC) element fully encapsulated by and chemically bonded to an encapsulation layer; and  
a hardfacing material bonded to the outer surface of the downhole tool and the encapsulation layer to attach the BDC construct to the plug section.   
   
**Regarding claim 15**. The downhole tool of claim 14, wherein the downhole tool is one of a group consisting of a drill bit, a push the bit pad, and a mud motor bearing assembly.   
   
**Regarding claim 16**. The downhole tool of claim 14, wherein the BDC construct includes a domed shaped face protruding from the outer surface of the downhole tool.   
   
**Regarding claim 17**. The downhole tool of claim 14, wherein the encapsulation layer has a lower thermal conductivity than the BDC element.   
   
**Regarding claim 18**. The downhole tool of claim 14, further comprising a binder cloth disposed over the plug section and a matrix cloth over the binder cloth.   
   
**Regarding claim 19**. The downhole tool of claim 14, wherein the encapsulation layer is disposed asymmetrically on an outer surface of the BDC element.   
   
**Regarding claim 20**. The downhole tool of claim 14, wherein the encapsulation layer is constructed of a metallic material.